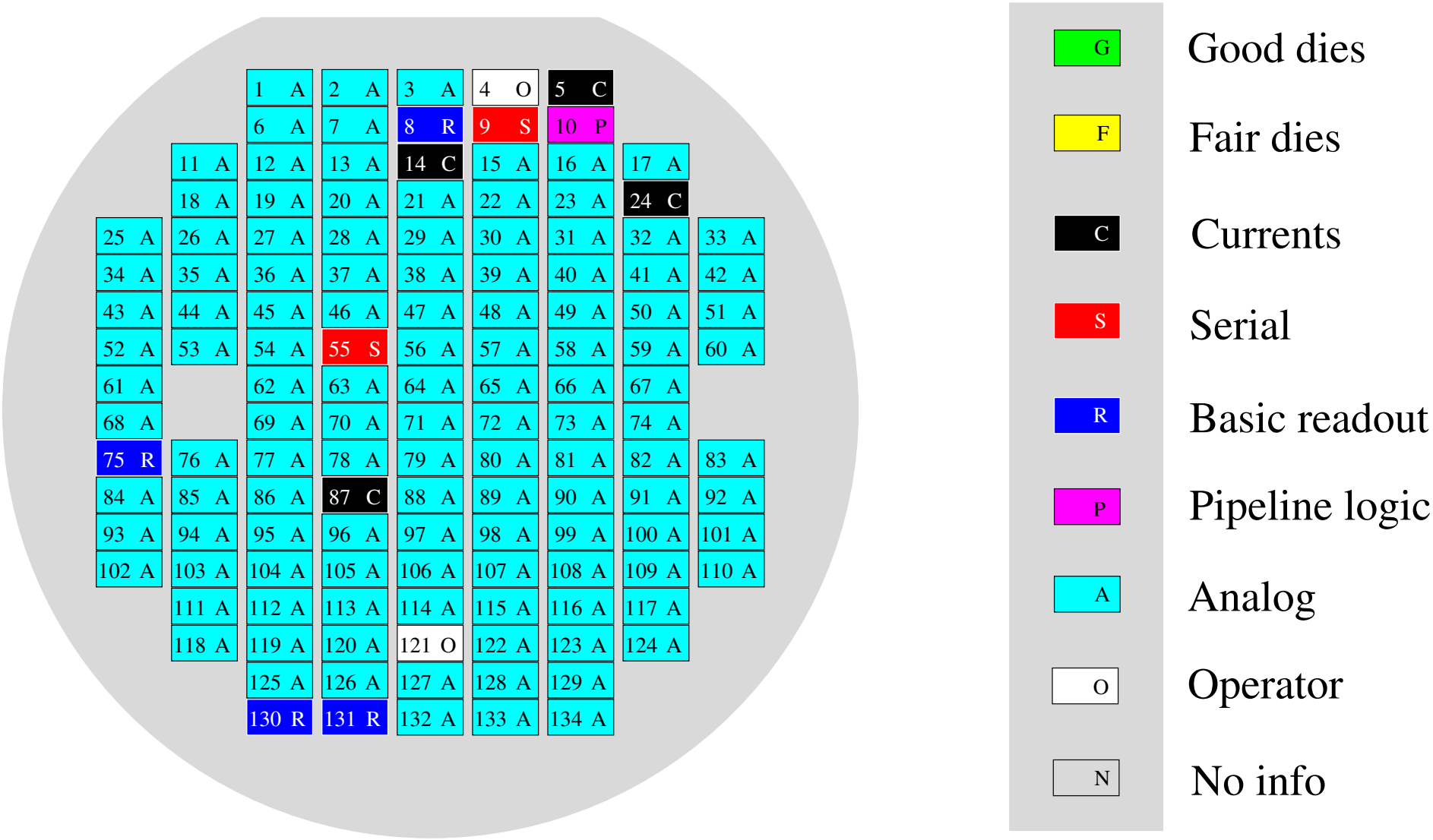
Types of die failures for wafer 89 s/n: Y21316-10-02 (not backplated)

Date: 04/05/99